

<b>L Number</b>	<b>Hits</b>	<b>S arch T xt</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>422</b>	<b>706/46</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/31 09:44</b>
<b>2</b>	<b>23</b>	<b>706/46 and @AD&lt;20000414 and @PD&gt;20021210</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/31 09:58</b>
<b>3</b>	<b>377</b>	<b>706/11</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/31 09:58</b>
<b>4</b>	<b>23</b>	<b>706/11 and @AD&lt;20000414 and @PD&gt;20021210</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/31 10:02</b>
<b>5</b>	<b>983</b>	<b>706/45</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/31 10:01</b>
<b>6</b>	<b>51</b>	<b>706/45 and @AD&lt;20000414 and @PD&gt;20021210</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/31 10:04</b>
<b>7</b>	<b>54</b>	<b>"knowledge base" and manufacturing and process and scalable</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/31 10:05</b>